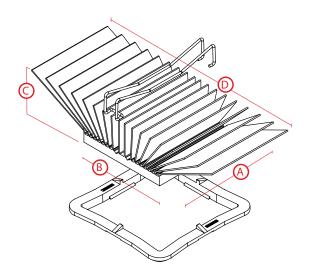


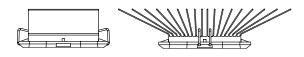
Ultra High Performance BGA Cooling Solutions w/ maxiGRIP™ Attachment

ATS PART # ATS-51400D-C2-R0

Features & Benefits

- » maxiFLOW™ design features a low profile, spread fin array that maximizes surface area for more effective convection (air) cooling
- » maxiGRIP™ attachment applies steady, even pressure to the component and does not require holes in the PCB
- » Meets Telcordia GR-63-Core Office Vibration; ETSI 300 019 Transportation Vibration; and MIL-STD-810 Shock and Unpackaged Drop Testing standards
- » Comes preassembled with high performance thermal interface material
- » Designed for low profile components from 1.5 to 2.99mm





Thermal Performance

*Image above is for illustration purposes only.

| AIR VELOCITY | | THERMAL RESISTANCE | | |
|--------------|-----|----------------------|--------------------|--|
| FT/MIN | M/S | °C/W (UNDUCTED FLOW) | °C/W (DUCTED FLOW) | |
| 200 | 1.0 | 4.5 | 2.8 | |
| 300 | 1.5 | 3.4 | | |
| 400 | 2.0 | 2.9 | | |
| 500 | 2.5 | 2.6 | | |
| 600 | 3.0 | 2.4 | | |
| 700 | 3.5 | 2.2 | | |
| 800 | 4.0 | 2 | | |

Product Details

| DIMENSION A | DIMENSION B | DIMENSION C | DIMENSION D | INTERFACE MATERIAL | FINISH |
|-------------|-------------|-------------|-------------|--------------------|-----------------|
| 40 mm | 40 mm | 9.5 mm | 56.5 mm | SAINT-GOBAIN C675 | BLACK- ANODIZED |

NOTES:

- Dimension C = heat sink height from bottom of the base to the top of the fin field.
- Thermal performance data are provided for reference only. Actual performance may vary by application.
- ATS reserves the right to update or change its products without notice to improve the design or performance.
- 4) Optional maxiGRIP™ Installation/Removal Tool Set P/N: MGT400
- 5) Contact ATS to learn about custom options available.



For more information, to find a distributor or to place an order, visit www.qats.com or call: 781.769.2800 (North America); +31 (0) 3569 84715 (Europe).